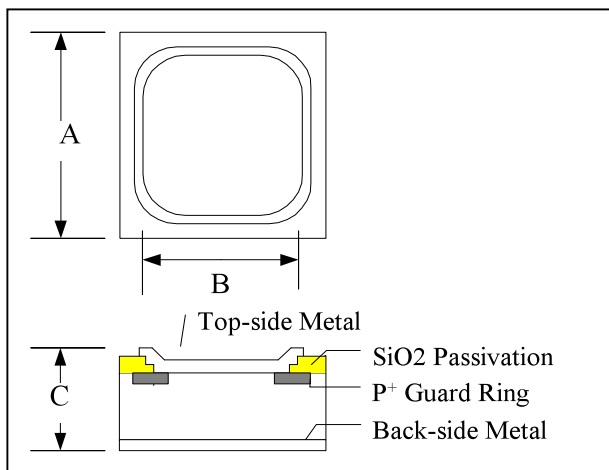


<b>ELECTRICAL CHARACTERISTICS</b>	<b>SYM</b>	<b>Spec. Limit</b>	<b>UNIT</b>
Reverse Breakdown Voltage: Ir=0.50mA	VBRM	65	Volt
Average Rectified Forward Current	IFAV	3.0	Amp
Maximum Instantaneous Forward Voltage			
@ 3 Amperes, Ta=25°C	VF MAX	0.58	Volt
Maximum Instantaneous Reverse Current			
VR= 65 Volt, Ta=25°C	IR MAX	0.100	mA
<b>MAXIMUM RATINGS</b>			
Nonrepetitive Peak Surge Current			
Semi-Sine Wave, Duty = 8.3ms · 1cycle	IFSM	80	Amp
Operating Junction Temperature	Tj	125	°C
Storage Temperatures	TSTG	-50 to +125	°C

1. Specification is applied to die only. Actual performance may degrade when assembled. BW does not guarantee device performance after assembly.
2. Suggest to storage in Nitrogen cabinet, 45-60% RH, 22-26 °C for 6 months.
3. Data sheet information is subjected to change without notice.
4. Suggest Soldering profile (Pb92.5%,5%Sn,Ag2.5%): Soldering peak Temp. 340~350 °C 3~5min.

DICE OUTLINE DRAWING



<b>DIM</b>	<b>ITEM</b>	<b>μ m</b>	<b>Mil</b>
A	Die Size	1397	55.00
B	Top Metal Pad Size	1197	47.13
C	Thickness	280	11.00

(1) Cutting street width is around 60μm.  
 (2) Both of top-side and back-side metals are Ti/Ni/Ag.  
 (3) Top-side Ti/Ni thk: 0.42μm, Ag thk: 3.5μm  
 (4) Thickness(C) tolerance: +/-10μm